



**GP**  
**ELECTRONICS**

**GPCD2008**

**20V Dual N-Channel MOSFET**

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
20V	14mΩ@4.5V	7A
	19mΩ@2.5V	

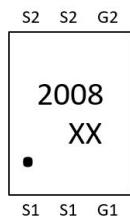
### Feature

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- ESD Protected

### Application

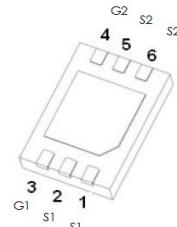
- Load Switch
- DC/DC Converter

### MARKING:

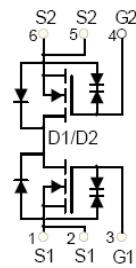


2008 = Device Cod  
XX = Date Code

**DFN2×3-6L**



**Schematic diagram**



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	20	V
Gate - Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>1,5</sup>	$I_D$	7	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	28	A
Power Dissipation <sup>4,5</sup>	$P_D$	1.5	W
Thermal Resistance from Junction to Ambient <sup>5</sup>	$R_{\theta JA}$	125	°C/W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55~+150	°C

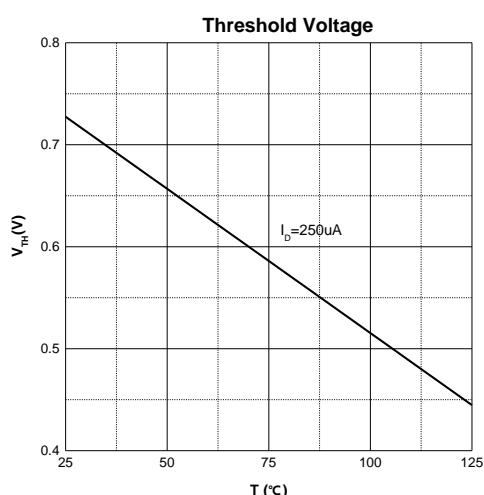
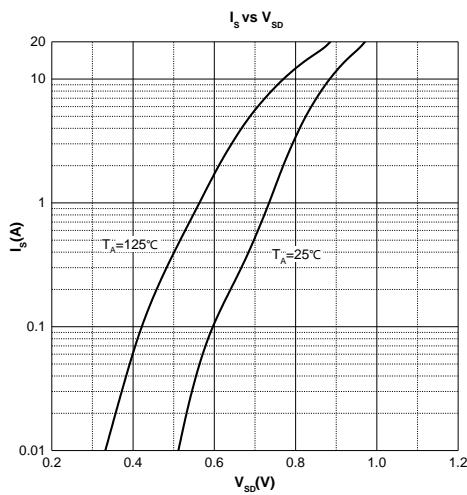
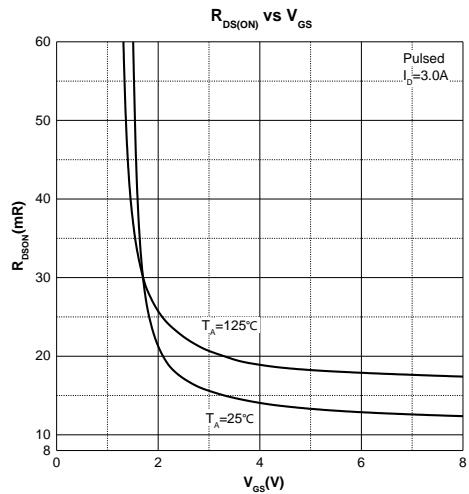
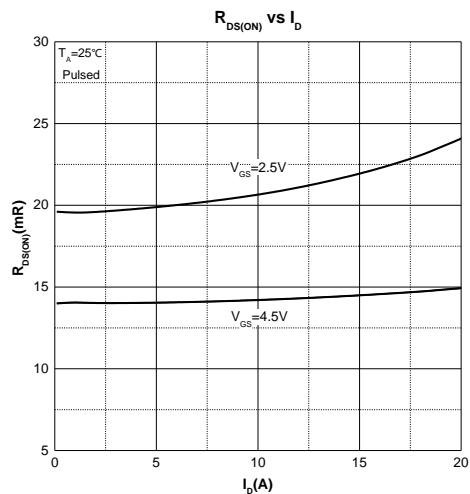
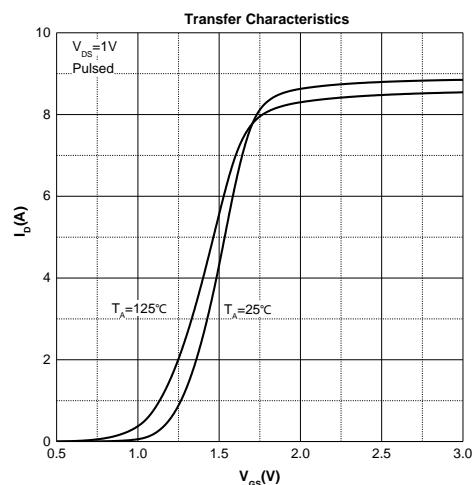
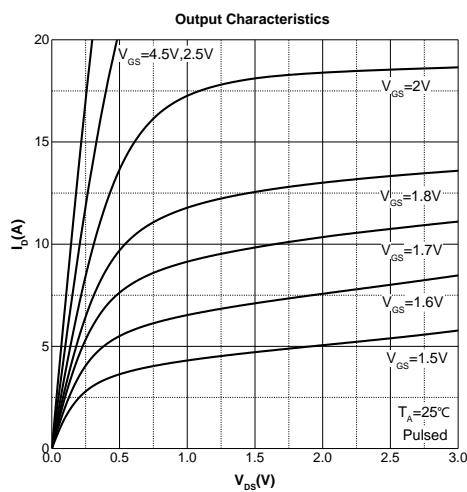
**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**

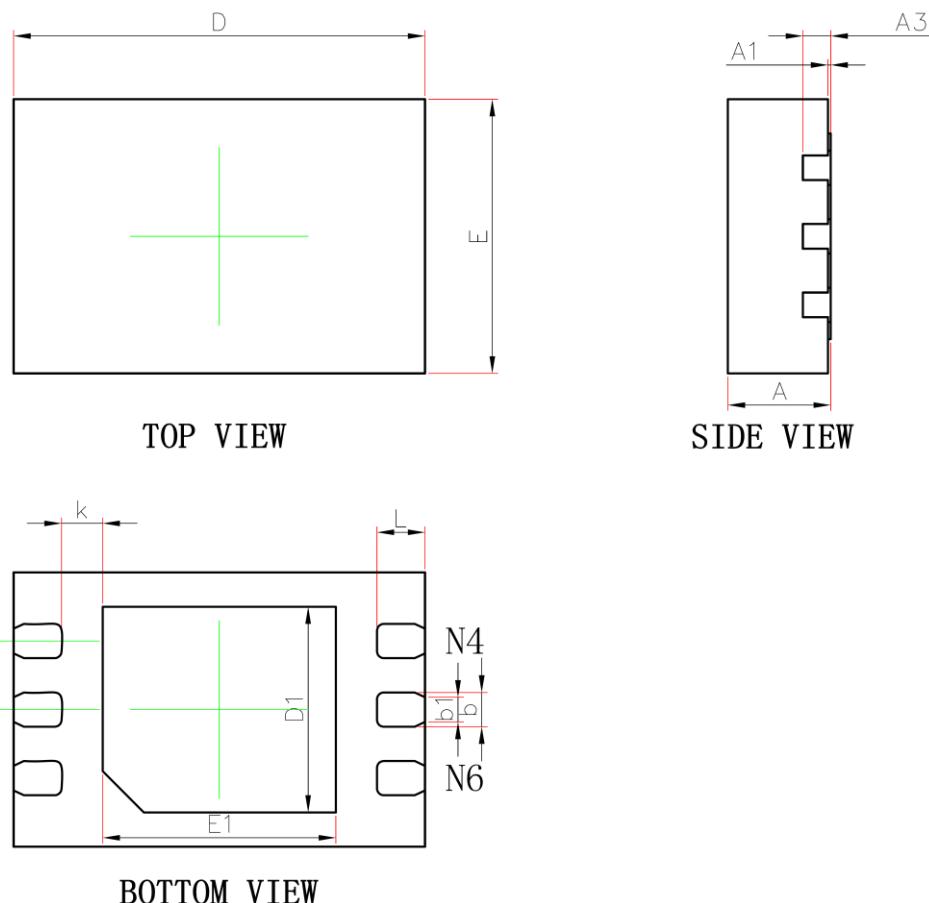
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate - Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 4$	$\mu\text{A}$
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.5	0.7	1.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 3\text{A}$		14	20	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 3\text{A}$		19	27	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, f = 0.1\text{MHz}$		494		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			97		
Reverse Transfer Capacitance	$C_{\text{rss}}$			10		
Gate Resistance	$R_g$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 0.1\text{MHz}$		2938		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 4.5\text{V}, I_D = 2\text{A}$		10.4		$\text{nC}$
Gate-source Charge	$Q_{gs}$			0.8		
Gate-drain Charge	$Q_{gd}$			4.7		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{\text{DD}} = 10\text{V}, V_{\text{GS}} = 5\text{V}, R_L = 1.35\Omega, R_G = 3\Omega$		2.5		$\text{ns}$
Turn-on Rise Time	$t_r$			7		
Turn-off Delay Time	$t_{d(\text{off})}$			47		
Turn-off Fall Time	$t_f$			102		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = 0.3\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width  $\leq 10\mu\text{s}$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .
- 5.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Characteristics



**DFN2x3-6L Package Information**


<b>Symbol</b>	<b>Dimensions In Millimeters</b>		<b>Dimensions In Inches</b>	
	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF		0.008REF	
D	2.900	3.100	0.114	0.122
E	1.900	2.100	0.075	0.083
D1	1.400	1.600	0.055	0.063
E1	1.600	1.800	0.063	0.071
b	0.200	0.300	0.008	0.012
k	0.150	0.350	0.006	0.014
b1	0.180REF		0.007REF	
e	0.500BSC		0.020BSC	
L	0.300	0.450	0.012	0.018